Abstract

An integrated circuit package is provided with increased resistance to the popcorn cracking effect. This package comprises an insulating substrate, which further comprises a first side to which an integrated circuit is mounted, and a second, opposite side. The substrate includes a plurality of conducting paths extending from the first side through the substrate, to the second side, and are further connected to a plurality of solder balls. These solder balls are attached to the second side of the substrate. The substrate is provided with divider slots through the substrate between the first and second area on the substrate. The first area is the die attach area. The second area comprises the remainder of the substrate.

This Sheet Has Been Replaced

